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NOV 0 7 2005	0 7 2005 TRANSMITTAL LETTER (General - Patent Pending)			Docket No. SEC.1092	
Byung-Se SO et al.				Ţ	
Application No. 10/722,159	Filing Date 26 November 2003	Examiner Dilinh P. Nguyen	Customer No. 20987	Group Art Unit 2814	Confirmation No.
Title: MULTI-CHIP PACKAGE FOR REDUCING PARASITIC LOAD OF PIN					
COMMISSIONER FOR PATENTS:					
Formal Drawing in the above ident  ☑ No addition ☐ A check in t	ler 37 C.F.R. § 1.111 s (3 Replacement Shee ified application. al fee is required. the amount of r is hereby authorized	is attached.	Account No.		
☐ Cre☐ Cha☐ Cha☐ Payment by ☐ WARNING:		•			not be
Signature  KENNETH D. SPRINGER  Reg. No. 39,843			Dated: 7 No	vember 2005	
Volentine Francos & Whitt, P.L.L.C. One Freedom Square 11951 Freedom Drive, Suite 1260 Reston, VA 20190 Tel. No. 571-283-0720			I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on		

cc:

(Date)

Signature of Person Mailing Correspondence

Typed or Printed Name of Person Mailing Correspondence



Application No. 10/722,159

SEC.1092 Amendment dated 7 November 2005

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent application of

Byung-Se SO et al. : Group Art Unit 2814

Application No. 10/722,159 : Examiner Dilinh P. NGUYEN

Filed 26 November 2003 :

MULTI-CHIP PACKAGE FOR

REDUCING PARASITIC LOAD OF PIN

## **AMENDMENT UNDER 37 C.F.R. § 1.111**

U.S. Patent and Trademark Office Customer Window, Mail Stop Amendment Randolph Building 401 Dulany Street Alexandria, VA 22314

Sir:

In response to the Office Action of 9 August 2005, the period for response to which extends through 9 November 2005, please amend the above-identified application as follows:

Amendments to the Drawings begin on page 2 of this paper and include attached replacement sheets.

Remarks begin on page 3 of this paper.

An **Appendix** including amended drawing figures is attached following page 11 of this paper.